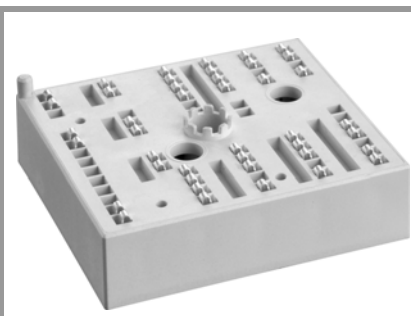


# SKiiP 24NAB176V1



MiniSKiiP® 2

3-phase bridge rectifier +  
brake chopper + 3-phase  
bridge inverter

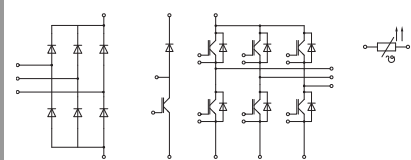
## SKiiP 24NAB176V1

### Features\*

- Trench IGBTs
- Robust and soft switching freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognized: File no. E63532
- NTC T-Sensor

### Remarks

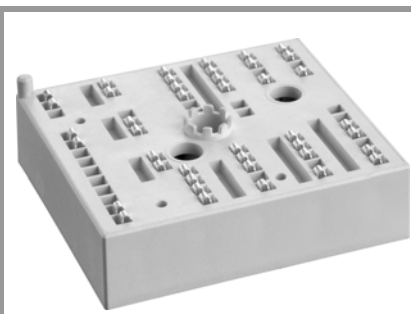
- Max. case temperature limited to  $T_C=125^\circ\text{C}$
- Product reliability results valid for  $T_j \leq 125^\circ\text{C}$  (recommended  $T_{j,op} = -40 \dots +125^\circ\text{C}$ )
- $I_{t(RMS)}$  limited to 20A for +B, B, -B, -DC/U, -DC/V, -DC/W power connectors
- The distance between terminals of temperature sensor and -DC/W is not sufficient for basic insulation
- The distance between terminals of +rect, +B and +DC not sufficient for basic insulation
- The distance between terminals of -B, -DC/U, DC/V and -DC/W not sufficient for basic insulation



NAB

Absolute Maximum Ratings				
Symbol	Conditions		Values	Unit
Inverter - IGBT				
V <sub>CES</sub>	T <sub>j</sub> = 25 °C		1700	V
I <sub>C</sub>	λ <sub>paste</sub> =0.8 W/(mK)	T <sub>s</sub> = 25 °C	38	A
	T <sub>j</sub> = 150 °C	T <sub>s</sub> = 70 °C	29	A
I <sub>C</sub>	λ <sub>paste</sub> =2.5 W/(mK)	T <sub>s</sub> = 25 °C	43	A
	T <sub>j</sub> = 150 °C	T <sub>s</sub> = 70 °C	33	A
I <sub>Cnom</sub>			29	A
I <sub>CRM</sub>			58	A
V <sub>GES</sub>			-20 ... 20	V
t <sub>psc</sub>	V <sub>CC</sub> = 1200 V V <sub>GE</sub> ≤ 20 V V <sub>CES</sub> ≤ 1700 V	T <sub>j</sub> = 125 °C	10	µs
T <sub>j</sub>			-55 ... 150	°C
Chopper - IGBT				
V <sub>CES</sub>	T <sub>j</sub> = 25 °C		1700	V
I <sub>C</sub>	λ <sub>paste</sub> =0.8 W/(mK)	T <sub>s</sub> = 25 °C	38	A
	T <sub>j</sub> = 150 °C	T <sub>s</sub> = 70 °C	29	A
I <sub>C</sub>	λ <sub>paste</sub> =2.5 W/(mK)	T <sub>s</sub> = 25 °C	43	A
	T <sub>j</sub> = 150 °C	T <sub>s</sub> = 70 °C	33	A
I <sub>Cnom</sub>			29	A
I <sub>CRM</sub>			58	A
V <sub>GES</sub>			-20 ... 20	V
t <sub>psc</sub>	V <sub>CC</sub> = 1200 V V <sub>GE</sub> ≤ 20 V V <sub>CES</sub> ≤ 1700 V	T <sub>j</sub> = 125 °C	10	µs
T <sub>j</sub>			-55 ... 150	°C
Inverse - Diode				
V <sub>RRM</sub>	T <sub>j</sub> = 25 °C		1700	V
I <sub>F</sub>	λ <sub>paste</sub> =0.8 W/(mK)	T <sub>s</sub> = 25 °C	48	A
	T <sub>j</sub> = 175 °C	T <sub>s</sub> = 70 °C	38	A
I <sub>F</sub>	λ <sub>paste</sub> =2.5 W/(mK)	T <sub>s</sub> = 25 °C	54	A
	T <sub>j</sub> = 175 °C	T <sub>s</sub> = 70 °C	43	A
I <sub>FRM</sub>			80	A
I <sub>FSM</sub>	t <sub>p</sub> = 10 ms, sin 180°, T <sub>j</sub> = 150 °C		280	A
T <sub>j</sub>			-40 ... 175	°C
Freewheeling - Diode				
V <sub>RRM</sub>	T <sub>j</sub> = 25 °C		1700	V
I <sub>F</sub>	λ <sub>paste</sub> =0.8 W/(mK)	T <sub>s</sub> = 25 °C	48	A
	T <sub>j</sub> = 175 °C	T <sub>s</sub> = 70 °C	38	A
I <sub>F</sub>	λ <sub>paste</sub> =2.5 W/(mK)	T <sub>s</sub> = 25 °C	54	A
	T <sub>j</sub> = 175 °C	T <sub>s</sub> = 70 °C	43	A
I <sub>FRM</sub>			80	A
I <sub>FSM</sub>	t <sub>p</sub> = 10 ms, sin 180°, T <sub>j</sub> = 150 °C		280	A
T <sub>j</sub>			-40 ... 175	°C

# SKiiP 24NAB176V1



MiniSKiiP® 2

3-phase bridge rectifier +  
brake chopper + 3-phase  
bridge inverter

## SKiiP 24NAB176V1

### Features\*

- Trench IGBTs
- Robust and soft switching freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognized: File no. E63532
- NTC T-Sensor

### Remarks

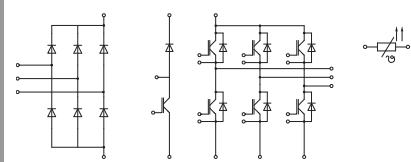
- Max. case temperature limited to  $T_C=125^\circ\text{C}$
- Product reliability results valid for  $T_j \leq 125^\circ\text{C}$  (recommended  $T_{j,op} = -40 \dots +125^\circ\text{C}$ )
- $I_{t(RMS)}$  limited to 20A for +B, B, -B, -DC/U, -DC/V, -DC/W power connectors
- The distance between terminals of temperature sensor and -DC/W is not sufficient for basic insulation
- The distance between terminals of +rect, +B and +DC not sufficient for basic insulation
- The distance between terminals of -B, -DC/U, DC/V and -DC/W not sufficient for basic insulation

### Absolute Maximum Ratings

Symbol	Conditions		Values	Unit
Rectifier - Diode				
V <sub>RRM</sub>	T <sub>j</sub> = 25 °C		1800	V
I <sub>F</sub>	λ <sub>paste</sub> =0.8 W/(mK)	T <sub>s</sub> = 25 °C	59	A
	T <sub>j</sub> = 150 °C	T <sub>s</sub> = 70 °C	42	A
I <sub>F</sub>	λ <sub>paste</sub> =2.5 W/(mK)	T <sub>s</sub> = 25 °C	66	A
	T <sub>j</sub> = 150 °C	T <sub>s</sub> = 70 °C	48	A
I <sub>FSM</sub>	t <sub>p</sub> = 10 ms	T <sub>j</sub> = 25 °C	370	A
	sin 180°	T <sub>j</sub> = 150 °C	270	A
i <sup>2</sup> t	t <sub>p</sub> = 10 ms	T <sub>j</sub> = 25 °C	685	A <sup>2</sup> s
	sin 180°	T <sub>j</sub> = 150 °C	365	A <sup>2</sup> s
T <sub>j</sub>			-40 ... 150	°C
Module				
I <sub>t(RMS)</sub>	T <sub>terminal</sub> = 80 °C, 20 A per spring		40	A
T <sub>stg</sub>	module without TIM		-40 ... 125	°C
V <sub>isol</sub>	AC sinus 50 Hz, 1 min		2500	V

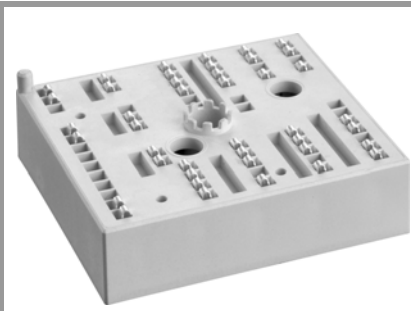
### Characteristics

Symbol	Conditions	min.	typ.	max.	Unit
<b>Inverter - IGBT</b>					
$V_{CE(sat)}$	$I_C = 29 \text{ A}$ $V_{GE} = 15 \text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$	2.00	2.45	V
		$T_j = 125^\circ\text{C}$	2.45	2.90	V
$V_{CE0}$	chipelevel	$T_j = 25^\circ\text{C}$	1.00	1.20	V
		$T_j = 125^\circ\text{C}$	0.90	1.10	V
$r_{CE}$	$V_{GE} = 15 \text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$	34	43	$\text{m}\Omega$
		$T_j = 125^\circ\text{C}$	53	62	$\text{m}\Omega$
$V_{GE(th)}$	$V_{GE} = V_{CE}$ , $I_C = 1.2 \text{ mA}$	5.2	5.8	6.4	V
$I_{CES}$	$V_{GE} = 0 \text{ V}$ , $V_{CE} = 1700 \text{ V}$ , $T_j = 25^\circ\text{C}$			1	mA
$C_{ies}$	$V_{CE} = 25 \text{ V}$ $V_{GE} = 0 \text{ V}$	$f = 1 \text{ MHz}$	2.50		nF
$C_{oes}$		$f = 1 \text{ MHz}$	0.11		nF
$C_{res}$		$f = 1 \text{ MHz}$	0.08		nF
$Q_G$	$V_{GE} = -8 \text{ V} \dots +15 \text{ V}$		240		nC
$R_{Gint}$	$T_j = 25^\circ\text{C}$		32		$\Omega$
$t_{d(on)}$	$V_{CC} = 900 \text{ V}$ $I_C = 20 \text{ A}$	$T_j = 125^\circ\text{C}$	290		ns
$t_r$	$R_{G on} = 1 \Omega$	$T_j = 125^\circ\text{C}$	40		ns
$E_{on}$	$R_{G off} = 1 \Omega$	$T_j = 125^\circ\text{C}$	5.1		mJ
$t_{d(off)}$	$di/dt_{on} = 580 \text{ A}/\mu\text{s}$	$T_j = 125^\circ\text{C}$	690		ns
$t_f$	$di/dt_{off} = 120 \text{ A}/\mu\text{s}$ $dv/dt = 4000 \text{ V}/\mu\text{s}$	$T_j = 125^\circ\text{C}$	120		ns
$E_{off}$	$V_{GE} = +15/-15 \text{ V}$ $L_s = 47 \text{ nH}$	$T_j = 125^\circ\text{C}$	6.3		mJ
$R_{th(j-s)}$	per IGBT, $\lambda_{paste}=0.8 \text{ W/(mK)}$		0.91		K/W
$R_{th(j-s)}$	per IGBT, $\lambda_{paste}=2.5 \text{ W/(mK)}$		0.73		K/W



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# SKiiP 24NAB176V1



MiniSKiiP® 2

3-phase bridge rectifier +  
brake chopper + 3-phase  
bridge inverter

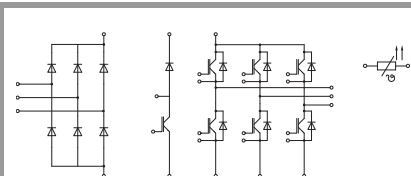
## SKiiP 24NAB176V1

### Features\*

- Trench IGBTs
- Robust and soft switching freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognized: File no. E63532
- NTC T-Sensor

### Remarks

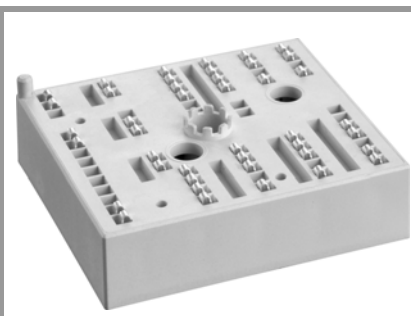
- Max. case temperature limited to  $T_C=125^\circ\text{C}$
- Product reliability results valid for  $T_j \leq 125^\circ\text{C}$  (recommended  $T_{j,op} = -40 \dots +125^\circ\text{C}$ )
- $I_{t(RMS)}$  limited to 20A for +B, B, -B, -DC/-U, -DC/V, -DC/W power connectors
- The distance between terminals of temperature sensor and -DC/W is not sufficient for basic insulation
- The distance between terminals of +rect, +B and +DC not sufficient for basic insulation
- The distance between terminals of -B, -DC/U, DC/V and -DC/W not sufficient for basic insulation



NAB

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Chopper - IGBT						
V <sub>CE(sat)</sub>	I <sub>C</sub> = 29 A	T <sub>J</sub> = 25 °C		2.00	2.45	V
	V <sub>GE</sub> = 15 V chiplevel	T <sub>J</sub> = 125 °C		2.45	2.90	V
V <sub>CE0</sub>	chiplevel	T <sub>J</sub> = 25 °C		1.00	1.20	V
		T <sub>J</sub> = 125 °C		0.90	1.10	V
r <sub>CE</sub>	V <sub>GE</sub> = 15 V chiplevel	T <sub>J</sub> = 25 °C		34	43	mΩ
		T <sub>J</sub> = 125 °C		53	62	mΩ
V <sub>GE(th)</sub>	V <sub>GE</sub> = V <sub>CE</sub> , I <sub>C</sub> = 1.2 mA		5.2	5.8	6.4	V
I <sub>CES</sub>	V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 1700 V, T <sub>J</sub> = 25 °C				1	mA
C <sub>ies</sub>	V <sub>CE</sub> = 25 V V <sub>GE</sub> = 0 V	f = 1 MHz		2.50		nF
C <sub>oes</sub>		f = 1 MHz		0.11		nF
C <sub>res</sub>		f = 1 MHz		0.08		nF
Q <sub>G</sub>	V <sub>GE</sub> = - 8 V...+ 15 V			240		nC
R <sub>Gint</sub>	T <sub>J</sub> = 25 °C			32		Ω
t <sub>d(on)</sub>	V <sub>CC</sub> = 900 V	T <sub>J</sub> = 125 °C		290		ns
t <sub>r</sub>	I <sub>C</sub> = 20 A	T <sub>J</sub> = 125 °C		40		ns
E <sub>on</sub>	R <sub>G on</sub> = 1 Ω	T <sub>J</sub> = 125 °C		5.1		mJ
t <sub>d(off)</sub>	R <sub>G off</sub> = 1 Ω	T <sub>J</sub> = 125 °C				
	di/dt <sub>on</sub> = 580 A/μs	T <sub>J</sub> = 125 °C		690		ns
t <sub>f</sub>	di/dt <sub>off</sub> = 120 A/μs	T <sub>J</sub> = 125 °C		120		ns
	dv/dt = 4000 V/μs					
E <sub>off</sub>	V <sub>GE</sub> = +15/-15 V L <sub>s</sub> = 47 nH	T <sub>J</sub> = 125 °C		6.3		mJ
R <sub>th(j-s)</sub>	per IGBT, λ <sub>paste</sub> =0.8 W/(mK)			0.91		K/W
R <sub>th(j-s)</sub>	per IGBT, λ <sub>paste</sub> =2.5 W/(mK)			0.73		K/W
Inverse - Diode						
V <sub>F</sub> = V <sub>EC</sub>	I <sub>F</sub> = 40 A	T <sub>J</sub> = 25 °C		2.00	2.38	V
	V <sub>GE</sub> = 0 V chiplevel	T <sub>J</sub> = 150 °C		2.14	2.56	V
V <sub>F0</sub>	chiplevel	T <sub>J</sub> = 25 °C		1.32	1.56	V
		T <sub>J</sub> = 150 °C		1.08	1.22	V
r <sub>F</sub>	chiplevel	T <sub>J</sub> = 25 °C		17	20	mΩ
		T <sub>J</sub> = 150 °C		27	33	mΩ
I <sub>RRM</sub>	I <sub>F</sub> = 20 A	T <sub>J</sub> = 125 °C		32.7		A
Q <sub>rr</sub>	di/dt <sub>off</sub> = 620 A/μs	T <sub>J</sub> = 125 °C		8.7		μC
E <sub>rr</sub>	V <sub>GE</sub> = -15 V V <sub>CC</sub> = 900 V	T <sub>J</sub> = 125 °C		4.9		mJ
R <sub>th(j-s)</sub>	per Diode, λ <sub>paste</sub> =0.8 W/(mK)			1.14		K/W
R <sub>th(j-s)</sub>	per Diode, λ <sub>paste</sub> =2.5 W/(mK)			0.95		K/W
Freewheeling - Diode						
V <sub>F</sub> = V <sub>EC</sub>	I <sub>F</sub> = 40 A	T <sub>J</sub> = 25 °C		2.00	2.38	V
	V <sub>GE</sub> = 0 V chiplevel	T <sub>J</sub> = 150 °C		2.14	2.56	V
V <sub>F0</sub>	chiplevel	T <sub>J</sub> = 25 °C		1.32	1.56	V
		T <sub>J</sub> = 150 °C		1.08	1.22	V
r <sub>F</sub>	chiplevel	T <sub>J</sub> = 25 °C		17	20	mΩ
		T <sub>J</sub> = 150 °C		27	33	mΩ
I <sub>RRM</sub>	I <sub>F</sub> = 20 A	T <sub>J</sub> = 125 °C		32.7		A
Q <sub>rr</sub>	di/dt <sub>off</sub> = 620 A/μs	T <sub>J</sub> = 125 °C		8.7		μC
E <sub>rr</sub>	V <sub>GE</sub> = -15 V V <sub>CC</sub> = 900 V	T <sub>J</sub> = 125 °C		4.9		mJ
R <sub>th(j-s)</sub>	per Diode, λ <sub>paste</sub> =0.8 W/(mK)			1.14		K/W
R <sub>th(j-s)</sub>	per Diode, λ <sub>paste</sub> =2.5 W/(mK)			0.95		K/W

# SKiiP 24NAB176V1



MiniSKiiP® 2

3-phase bridge rectifier +  
brake chopper + 3-phase  
bridge inverter

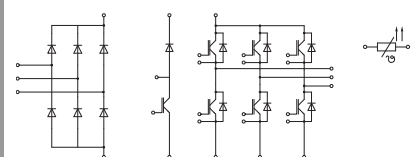
## SKiiP 24NAB176V1

### Features\*

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- Robust and soft switching freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognized: File no. E63532
- NTC T-Sensor

### Remarks

- Max. case temperature limited to  $T_C=125^\circ\text{C}$
- Product reliability results valid for  $T_j \leq 125^\circ\text{C}$  (recommended  $T_{j,op} = -40 \dots +125^\circ\text{C}$ )
- $I_{t(RMS)}$  limited to 20A for +B, B, -B, -DC/U, -DC/V, -DC/W power connectors
- The distance between terminals of temperature sensor and -DC/W is not sufficient for basic insulation
- The distance between terminals of +rect, +B and +DC not sufficient for basic insulation
- The distance between terminals of -B, -DC/U, DC/V and -DC/W not sufficient for basic insulation



NAB

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Rectifier - Diode						
V <sub>F</sub> = V <sub>EC</sub>	I <sub>F</sub> = 41 A chiplevel	T <sub>j</sub> = 25 °C		1.19	1.45	V
		T <sub>j</sub> = 125 °C		1.17	1.42	V
V <sub>F0</sub>	chiplevel	T <sub>j</sub> = 25 °C	0.6	0.87	1.10	V
		T <sub>j</sub> = 125 °C		0.75	0.97	V
r <sub>F</sub>	chiplevel	T <sub>j</sub> = 25 °C		7.9	8.7	mΩ
		T <sub>j</sub> = 125 °C		10	11	mΩ
I <sub>R</sub>	T <sub>j</sub> = 145 °C, V <sub>RRM</sub>				1.1	mA
R <sub>th(j-s)</sub>	per Diode, λ <sub>paste</sub> =0.8 W/(mK)			1.32		K/W
R <sub>th(j-s)</sub>	per Diode, λ <sub>paste</sub> =2.5 W/(mK)			1.12		K/W
Module						
M <sub>s</sub>	to heat sink		2		2.5	Nm
w				55		g
L <sub>CE</sub>				31		nH
Temperature Sensor						
R <sub>100</sub>	T <sub>r</sub> =100°C (R <sub>25</sub> =1000Ω)			1670 ± 3%		Ω
R <sub>(T)</sub>	R <sub>(T)</sub> =1000Ω[1+A(T-25°C)+B(T-25°C) <sup>2</sup> ] , A = 7.635*10 <sup>-3</sup> °C <sup>-1</sup> , B = 1.731*10 <sup>-5</sup> °C <sup>-2</sup>					

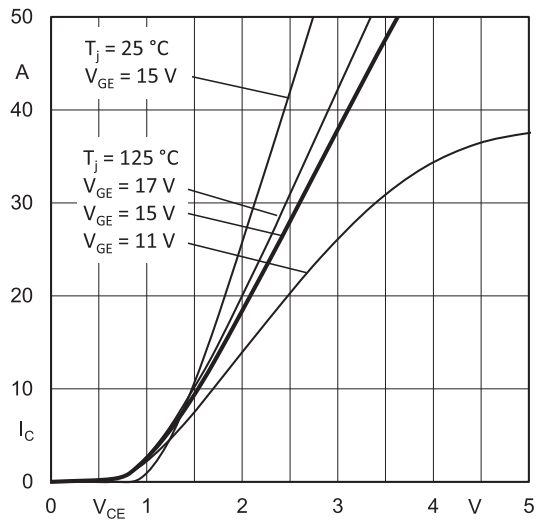


Fig. 1: Typ. output characteristic, inclusive  $R_{CC'} + E_{E'}$

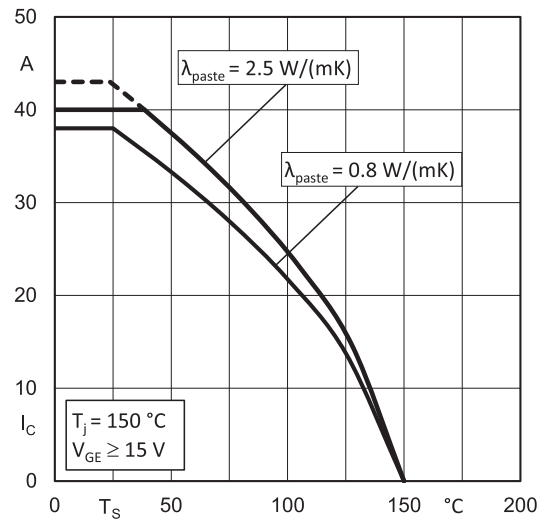


Fig. 2: Typ. rated current vs. temperature  $I_C = f(T_s)$

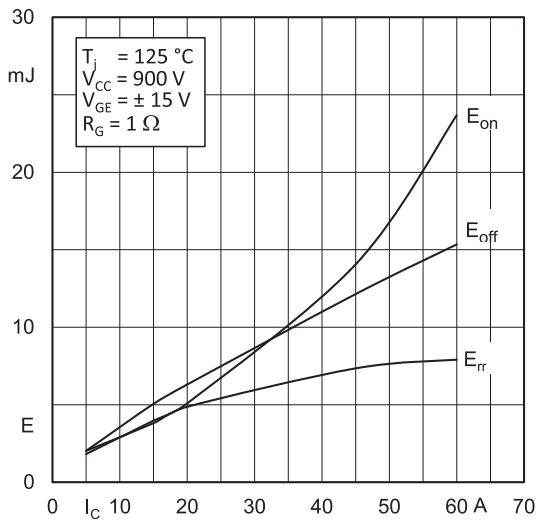


Fig. 3: Typ. turn-on /-off energy =  $f(I_C)$

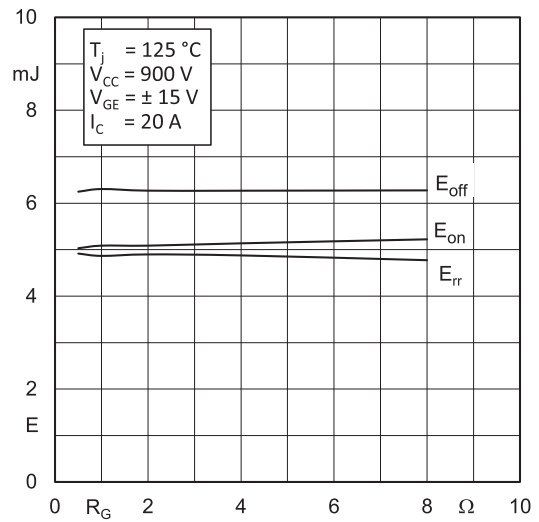


Fig. 4: Typ. turn-on /-off energy =  $f(R_G)$

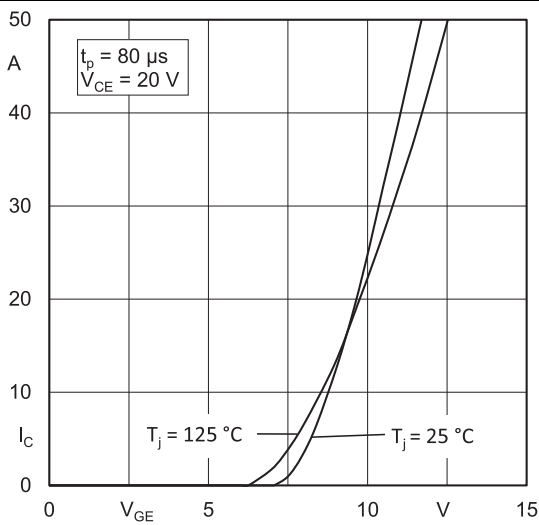


Fig. 5: Typ. transfer characteristic

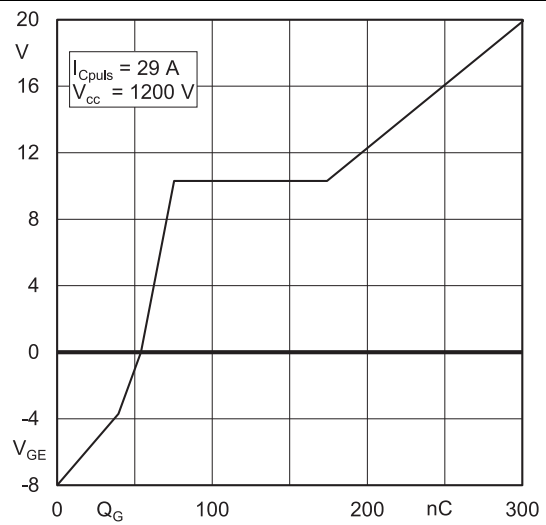


Fig. 6: Typ. gate charge characteristic

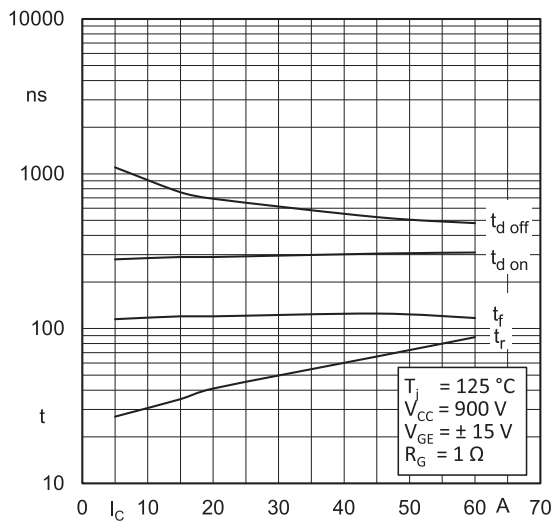


Fig. 7: Typ. switching times vs.  $I_C$

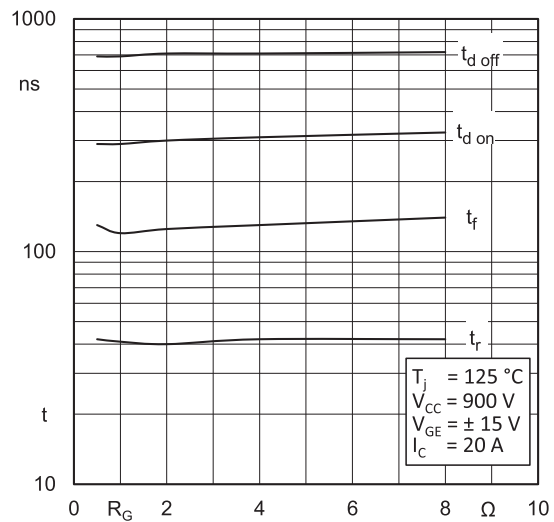


Fig. 8: Typ. switching times vs. gate resistor  $R_G$

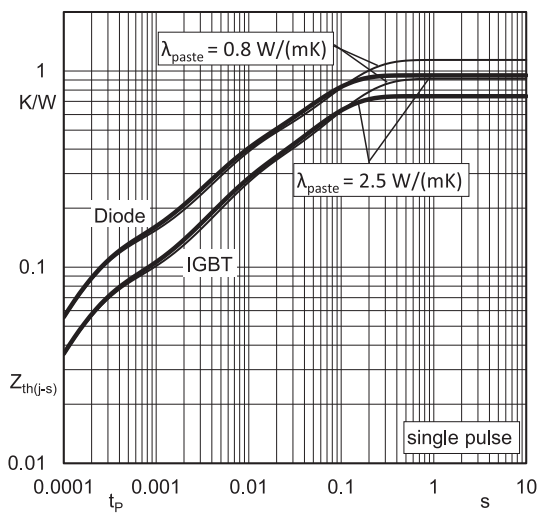


Fig. 9: Typ. transient thermal impedance

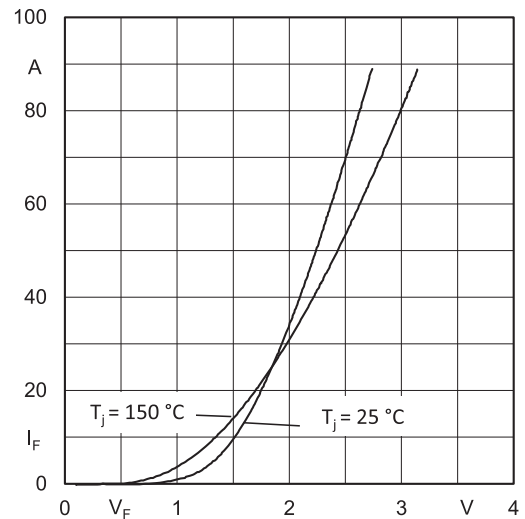


Fig. 10: Typ. CAL diode forward charact., incl.  $R_{CC'+EE'}$

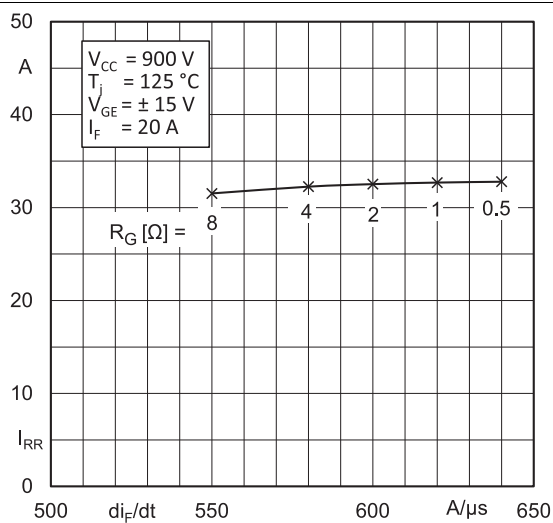


Fig. 11: Typ. CAL diode peak reverse recovery current

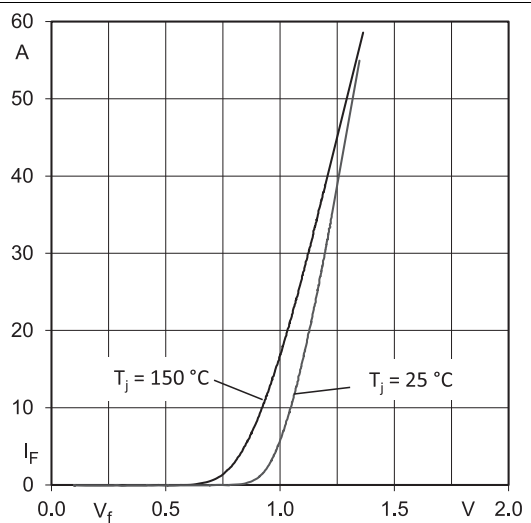
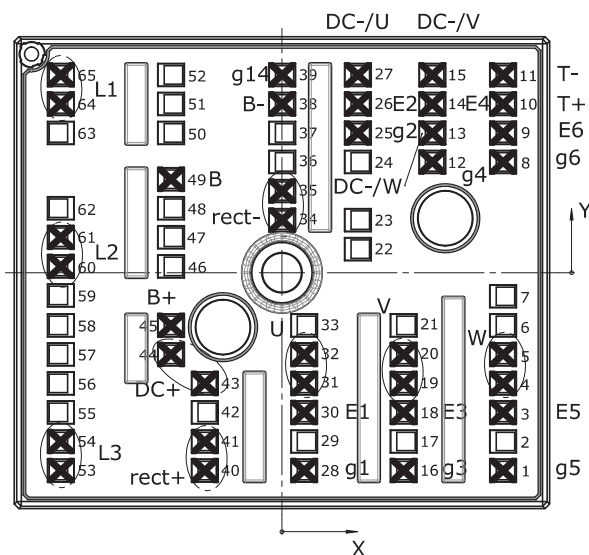


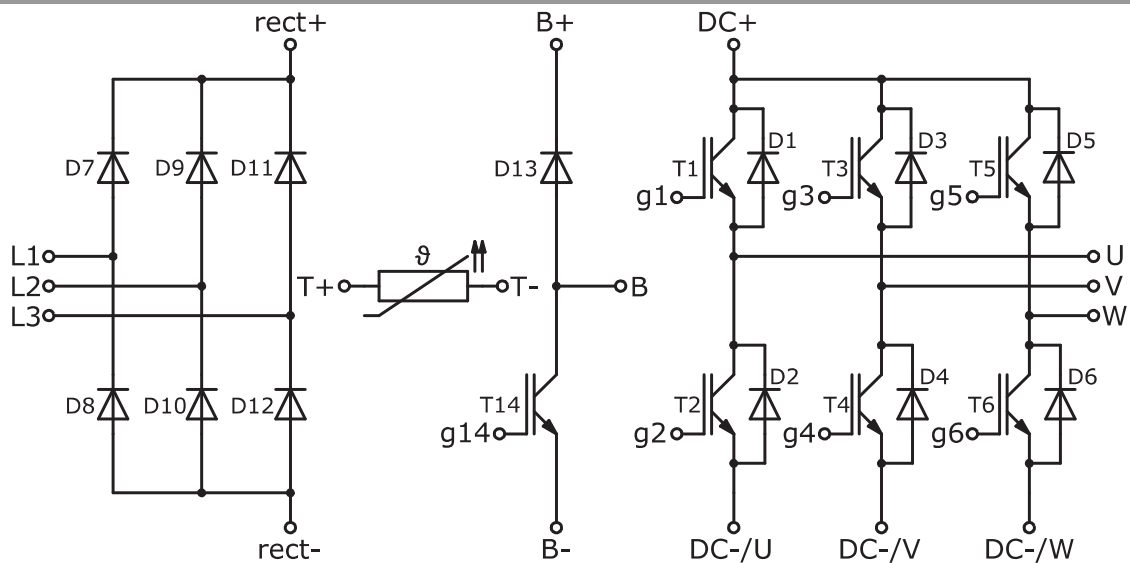
Fig. 12: Typ. input bridge forward characteristic incl.  $R_{CC'+EE'}$

Pin out											
Pin	X	Y	Function	Pin	X	Y	Function	Pin	X	Y	Function
1	24,38	-21,80	g5	23	8,38	5,80		45	-12,23	-5,80	B+
2	24,38	-18,60		24	8,38	12,20		46	-12,23	0,70	
3	24,38	-15,40	E5	25	8,38	15,40	g2	47	-12,23	3,90	
4	24,38	-12,20	W	26	8,38	18,60	E2	48	-12,23	7,10	
5	24,38	-9,00	W	27	8,38	21,80	DC-/U	49	-12,23	10,30	B
6	24,38	-5,80		28	2,46	-21,80	g1	50	-12,23	15,40	
7	24,38	-2,60		29	2,46	-18,60		51	-12,23	18,60	
8	24,38	12,20	g6	30	2,46	-15,40	E1	52	-12,23	21,80	
9	24,38	15,40	E6	31	2,46	-12,20	U	53	-24,38	-21,80	L3
10	24,38	18,60	T+	32	2,46	-9,00	U	54	-24,38	-18,60	L3
11	24,38	21,80	T-	33	2,46	-5,80		55	-24,38	-15,40	
12	16,58	12,20	g4	34	0,03	5,80	rect-	56	-24,38	-12,20	
13	16,58	15,40	DC-/W	35	0,03	9,00	rect-	57	-24,38	-9,00	
14	16,58	18,60	E4	36	0,03	12,20		58	-24,38	-5,80	
15	16,58	21,80	DC-/V	37	0,03	15,40		59	-24,38	-2,50	
16	13,42	-21,80	g3	38	0,03	18,60	B-	60	-24,38	0,70	L2
17	13,42	-18,60		39	0,03	21,80	g14	61	-24,38	3,90	L2
18	13,42	-15,40	E3	40	-8,51	-21,80	rect+	62	-24,38	7,10	
19	13,42	-12,20	V	41	-8,51	-18,60	rect+	63	-24,38	15,40	
20	13,42	-9,00	V	42	-8,51	-15,40		64	-24,38	18,60	L1
21	13,42	-5,80		43	-8,51	-12,20	DC+	65	-24,38	21,80	L1
22	8,38	2,60		44	-12,23	-9,00	DC+				

all values in mm



Pinout and Dimensions



Pinout

This is an electrostatic discharge sensitive device (ESDS) due to international standard IEC 61340.

## **\*IMPORTANT INFORMATION AND WARNINGS**

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